

ULTRA MINIATURE CERAMIC PACKAGE HIGH STABILITY SMD CRYSTAL



5.0 x 3.2 x 0.9mm

ABM3X



RoHS/RoHS II compliant

FEATURES:

- -40°C to +125°C wide operating temperature range
- ±40 ppm Max. All Inclusive frequency stability over 10-year product life
- Fundamental Mode, low ESR Quartz design
- Ultra miniature, Seam-Sealed, RoHS compliant reflow-able package

APPLICATIONS:

- Zigbee based designs for indoor / outdoor applications
- Wireless Sensor Networks
- Industrial Control
- Home and Building Automation
- Consumer Electronics
- PC Peripherals

STANDARD SPECIFICATIONS

Parameters	Minimum	Typical	Maximum	Units	Notes
Center Frequency		24.000 32.000		MHz	
Operation Mode	Fundamental				
Operating Temperature	-40		+125	°C	
Storage Temperature	-55		+155	°C	
Overall Frequency Stability (All inclusive)	-40		+40	ppm	
Frequency Tolerance	-10		+10	ppm	
Frequency Stability over the Operating Temperature Range (ref. to +25°C)	-25		+25	ppm	
Aging	-5		+5	ppm	@25±3°C 10 years
Equivalent series resistance (R1)			30	Ω	
Shunt capacitance (C0)			3.5	pF	
Motional capacitance (C1)		4.5		fF	
Load capacitance (CL)		10		pF	
Drive Level		50	100	μW	
Insulation Resistance	500			MΩ	@100Vdc±15V

OPTIONS AND PART IDENTIFICATION:

ABM3X - - - MHz -

Internal Code	Frequency
101	24.000 MHz
102	32.000 MHz

Packaging
Blank: Bulk
T: 1kpcs / reel

Example Part #: ABM3X-101-24.000MHz-T

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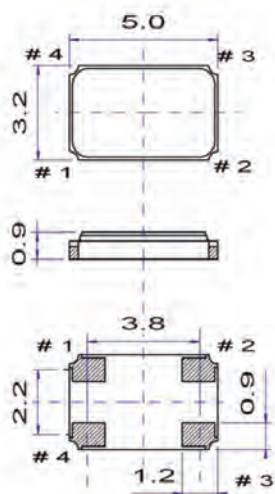
5.0 x 3.2 x 0.9mm

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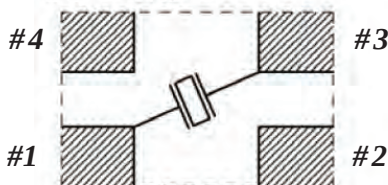
RoHS/RoHS II compliant

OUTLINE DIMENSIONS:



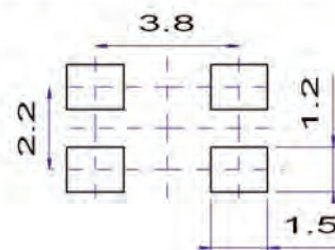
Pin function

- # 1 crystal connection
- # 2 GND
- # 3 crystal connection
- # 4 GND



Do not design any conductive path between the pattern

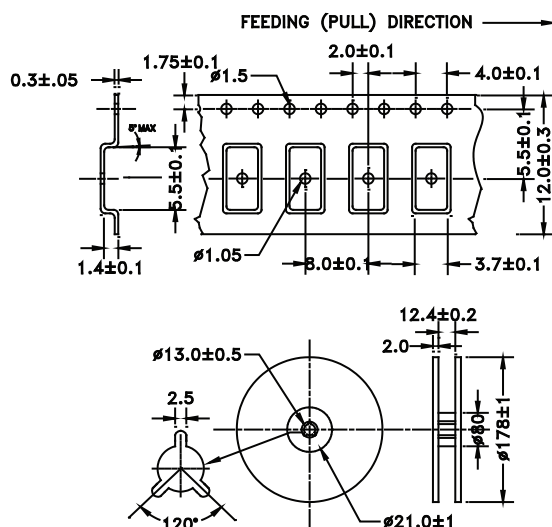
Example for solder pattern



Dimensions: mm

TAPE & REEL:

1000pcs/reel



Dimensions: mm

REFLOW PROFILE:

